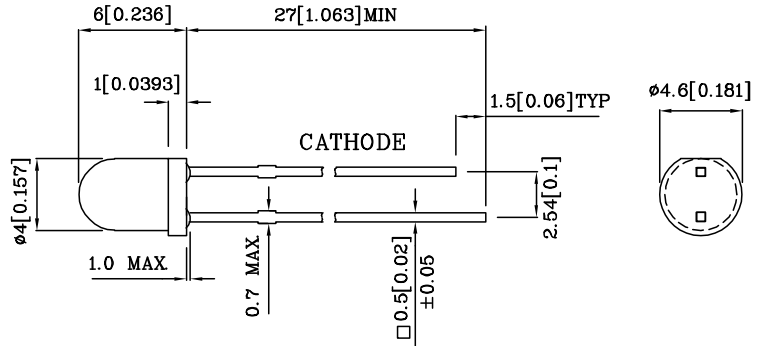


**Features**

- LOW POWER CONSUMPTION.
- VERSATILE MOUNTING ON P.C. BOARD OR PANEL.
- POPULAR 4mm DIAMETER.
- RELIABLE AND RUGGED.
- RoHS COMPLIANT.



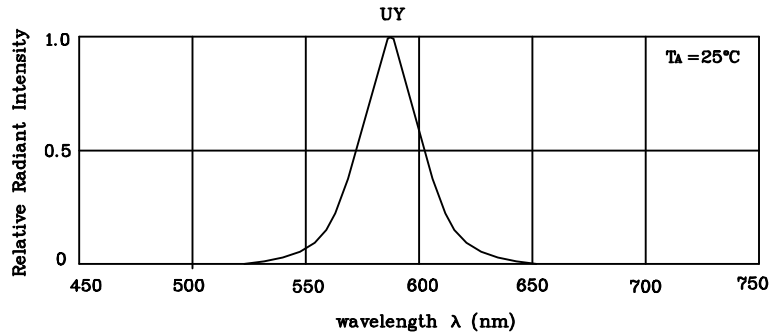
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.

Absolute maximum ratings (TA=25°C)		UY (GaAsP/ GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>T</sub>	105	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

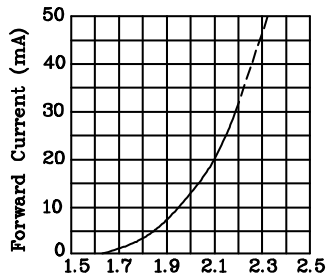
Operating Characteristics (TA=25°C)		UY (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	1.95	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission (I <sub>F</sub> =10mA)	λ <sub>P</sub>	590	nm
Wavelength of Dominant Emission (I <sub>F</sub> =10mA)	λ <sub>D</sub>	588	nm
Spectral Line Full Width At Half-Maximum (I <sub>F</sub> =10mA)	Δλ	35	nm
Capacitance (V <sub>F</sub> =0V, f=1MHz)	C	20	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =10mA) mcd		Wavelength nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XLUY44D	Yellow	GaAsP/GaP	Yellow Diffused	3	9	590	80°
Published Date : MAY 25,2005      Drawing No : XDSA2374      V3      Checked : B.L.LIU      P.1/3							

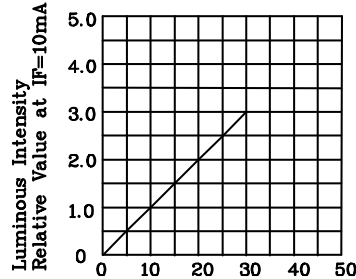


RELATIVE INTENSITY Vs. WAVELENGTH

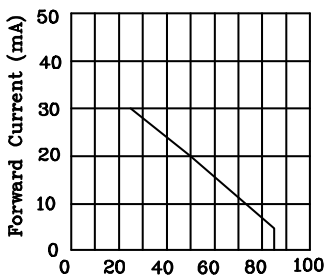
❖ UY



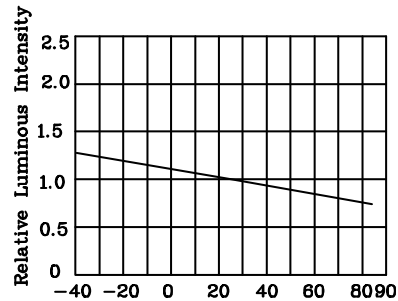
FORWARD CURRENT Vs. FORWARD VOLTAGE



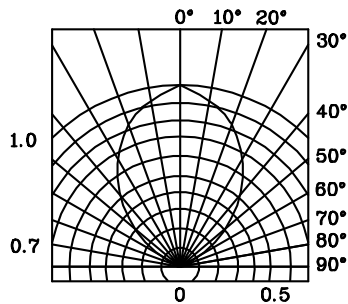
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE

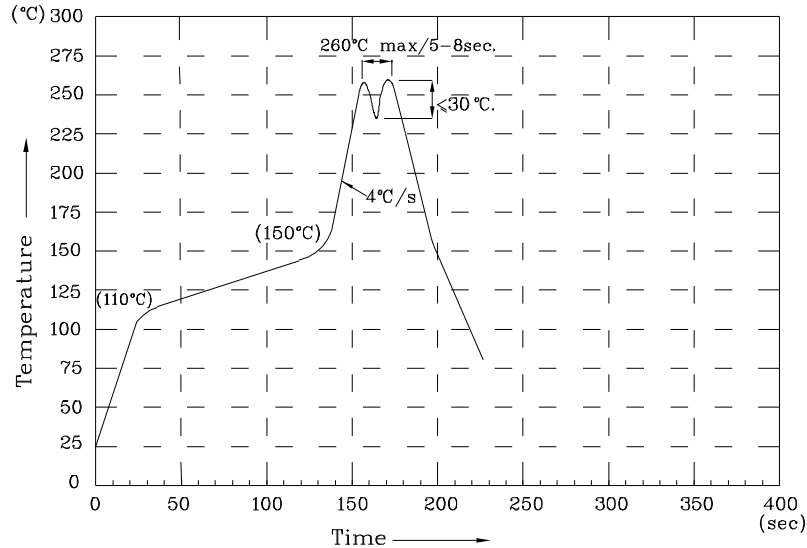


LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.